

A Gate-level Pipelined 2.97GHz Self Synchronous FPGA in 65nm CMOS

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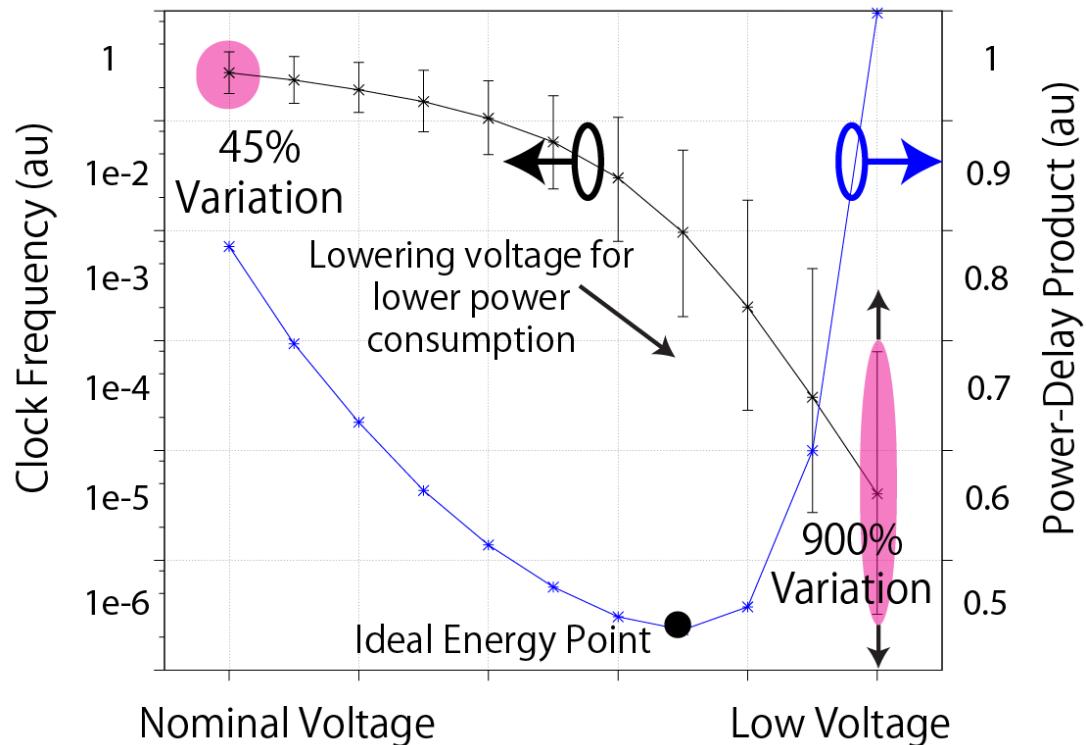


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Motivation

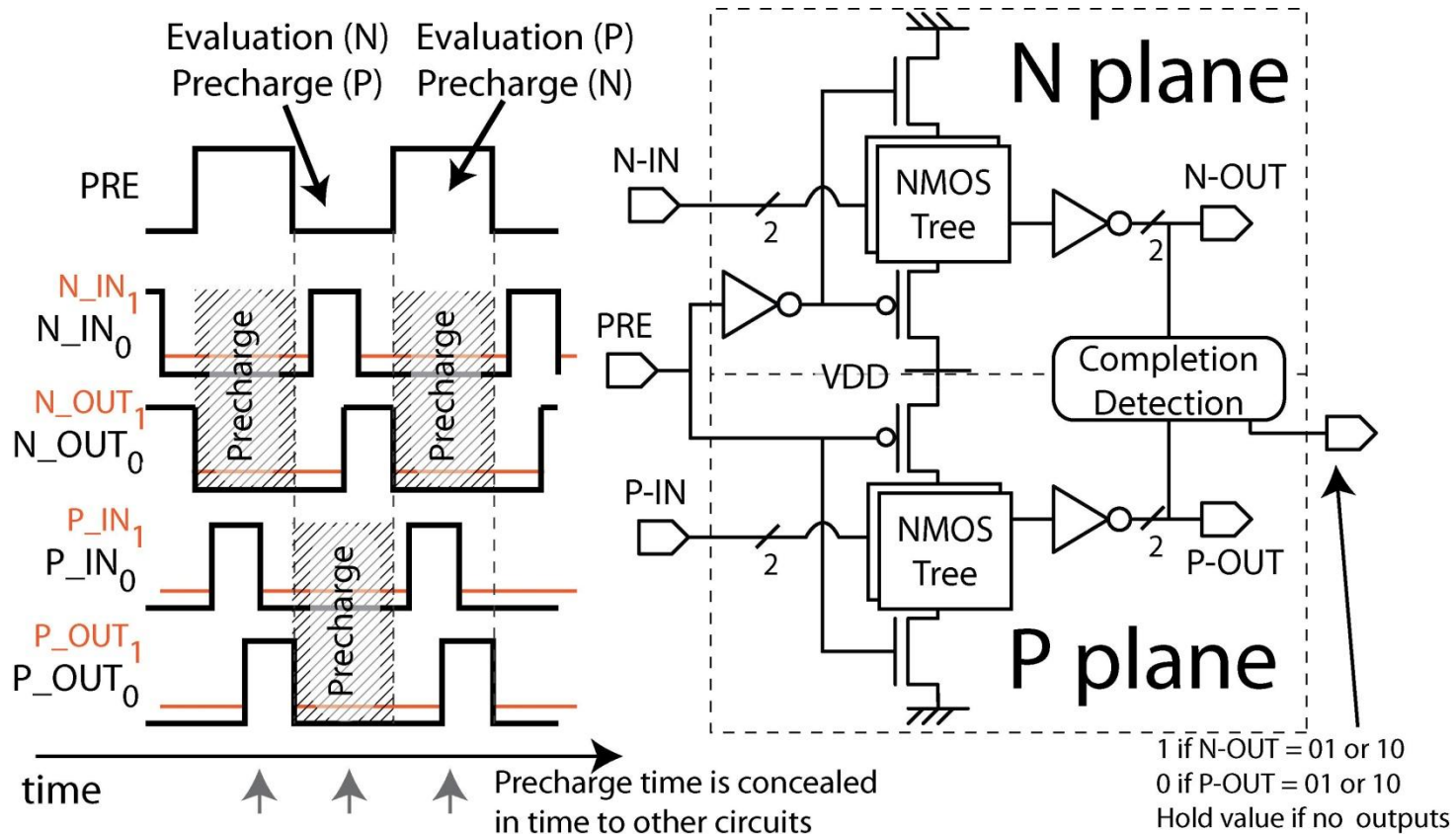
- Variation is increasing
- Want to operate at 'Ideal Energy Point'
 - Need PVT (process, voltage, temperature) variation robust systems

65nm Circuit Throughput Variation and Power-Delay Product



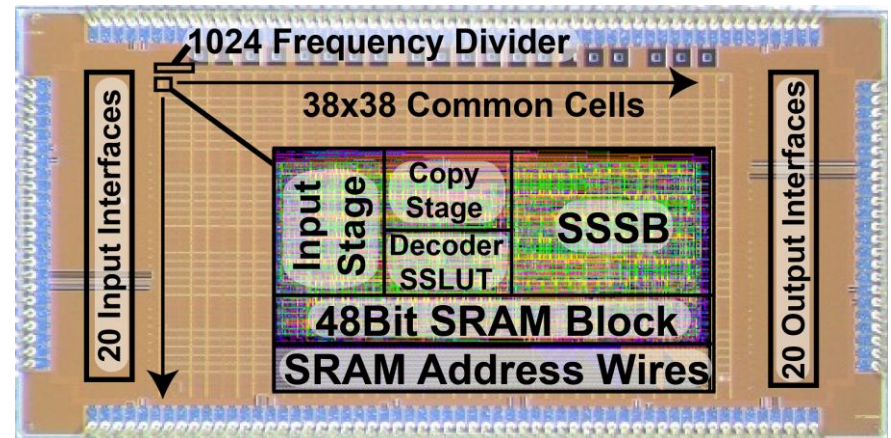
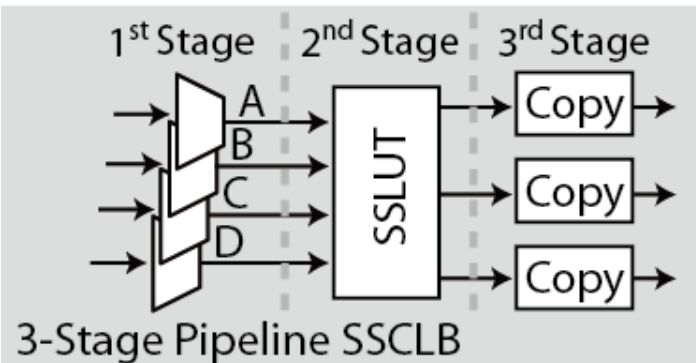
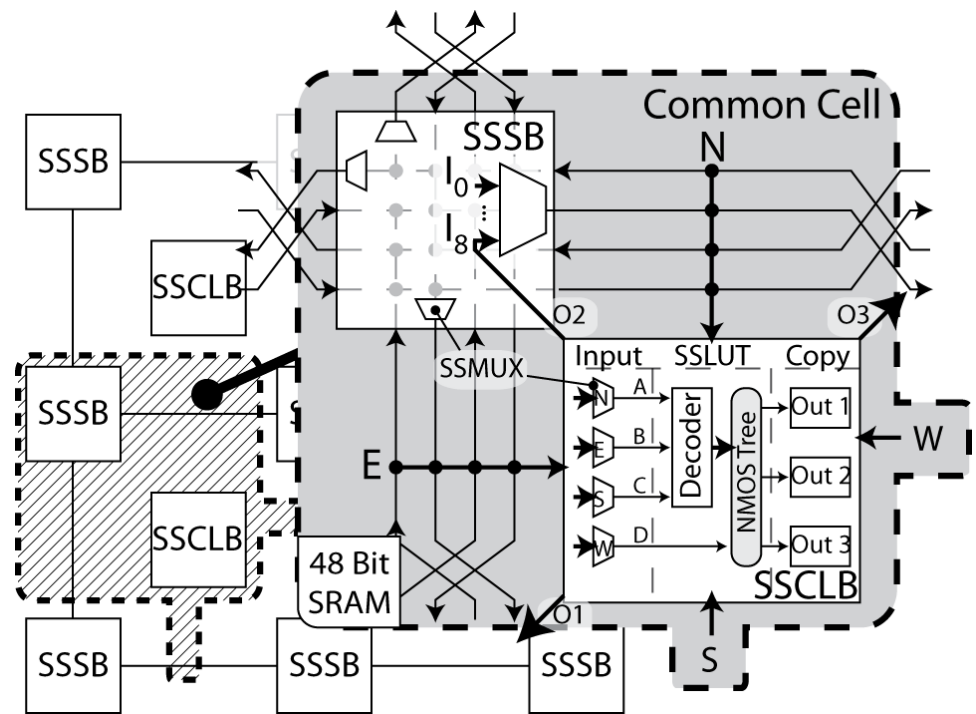
Dual Pipeline DCVSL

- Dual Pipeline conceals DCVSL precharge delay
- Self Synchronous operation with Completion detection for delay insensitivity



SSFPGA Chip

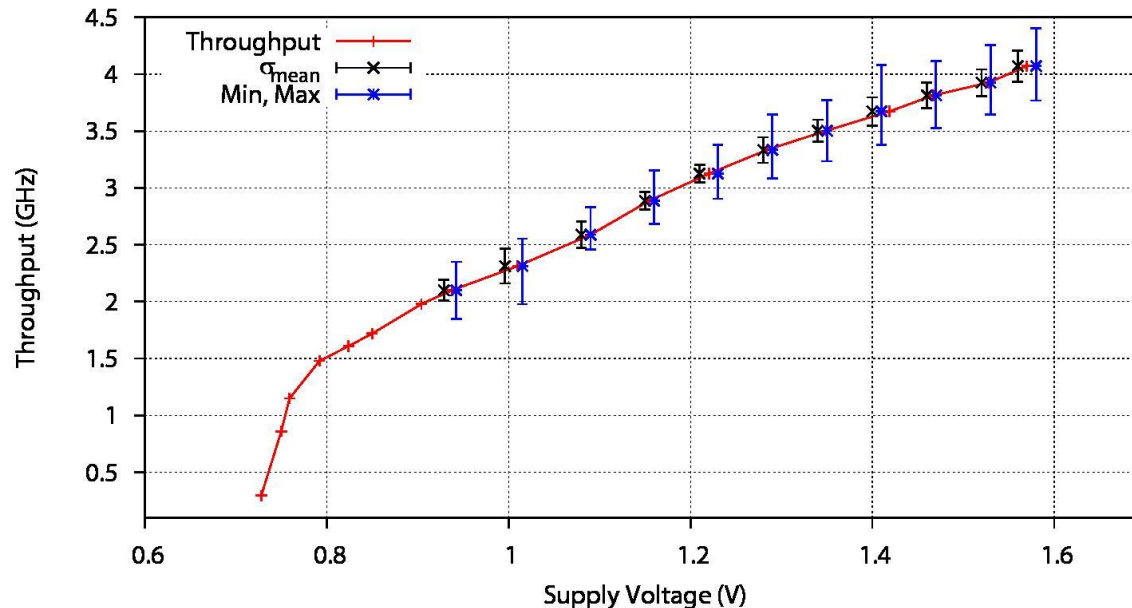
- A Self Synchronous FPGA was fabricated in 65nm and measured
- Dual Pipeline DCVSL, Completion Detection circuits
- Gate level Pipeline
- 4-input lookup table, 3-output, 4 channels



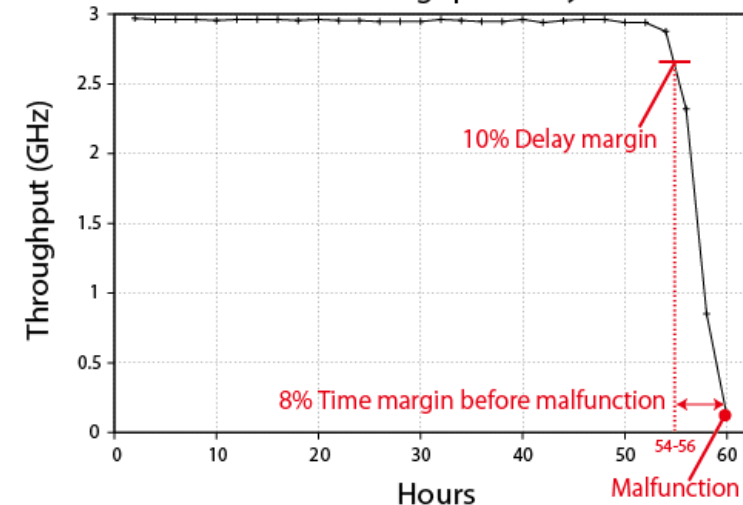
Measurement Results

- Throughput of 3GHz @ 1.2V (highest reported)
- Correct operation to 750mV, 0-120°C
- Self Synchronous Signaling improves aging characteristics, 8% longer compared to Synchronous System

Inter and Intra Chip-Chip Variation in Throughput vs Supply Voltage



SSFPGA Throughput vs Cycle



Conclusions

- The fabricated SSFPGA was measured against PVT variations, and showed **robust, correct operation over 750mV to 1.6V, 0°C to 80°C, with process variation**
- Aging measurements show correct operation **8% longer** past a 10% delay margin, until chip malfunction
- **This research shows Self Synchronous Circuits can offer Reliable, Ideal Energy Point Operation in nano-meter node processes for future VLSI systems**

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The VLSI chip in this study has been fabricated in the chip fabrication program of VLSI Design and Education Center (VDEC), the University of Tokyo in collaboration with STARC, e-Shuttle, Inc., and Fujitsu Ltd.